



GreenMOS™

## OSG80R250xF\_Datasheet



# Enhancement Mode N-Channel Power MOSFET

## Features

- ◆ Low  $R_{DS(on)}$  & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

## Applications

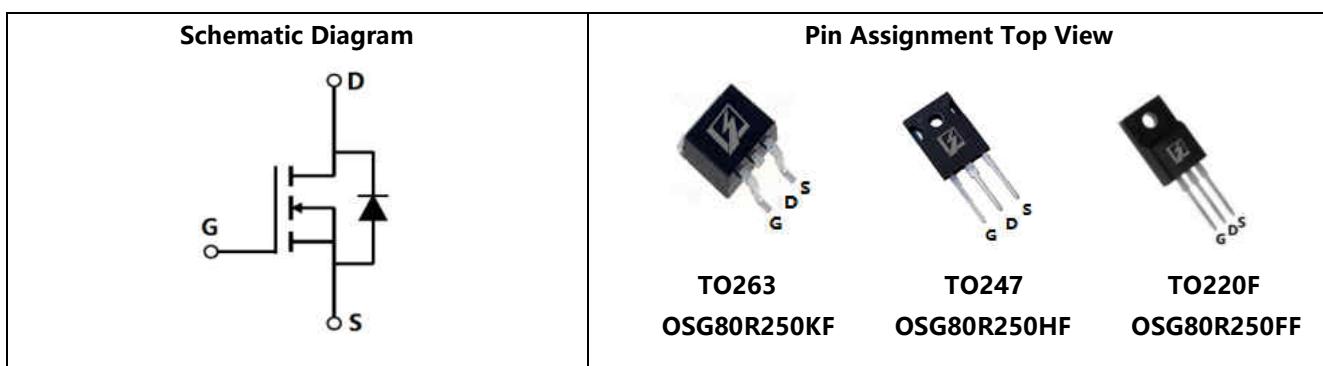
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

## ■ General Description

OSG80R250xF use advanced GreenMOS™ technology to provide low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ $V_{DS, min@Tjmax}$	850 V
◆ $I_D, pulse$	51 A
◆ $R_{DS(ON)}, \text{max } @ VGS=10 \text{ V}$	250 mΩ
◆ $Q_g$	41.2 nC

## ■ Schematic and Package Information



## ■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	800	V
Gate source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	17	A
Continuous drain current <sup>1)</sup> , $T_C=100^\circ\text{C}$		10.8	
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_D, \text{pulse}$	51	A
Power dissipation <sup>3)</sup> for TO263, TO247, $T_C=25^\circ\text{C}$	$P_D$	219	W
Power dissipation <sup>3)</sup> for TO220F, $T_C=25^\circ\text{C}$		34	
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	800	mJ
MOSFET dV/dt ruggedness, $V_{DS}=0...640 \text{ V}$	dV/dt	50	V/ns
Reverse diode dV/dt, $V_{DS}=0...640 \text{ V}$ , $I_{SD} \leq I_D$	dV/dt	15	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

## ■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO263/TO247	TO220F	
Thermal resistance, junction-case	$R_{\theta JC}$	0.57	3.68	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	62.5	°C/W

## ■ Electrical Characteristics at $T_j=25$ °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	800			V	$V_{GS}=0$ V, $I_D=250$ μA
		850				$V_{GS}=0$ V, $I_D=250$ μA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	2.9		3.9	V	$V_{DS}=V_{GS}$ , $I_D=250$ μA
Drain-source on-state resistance	$R_{DS(ON)}$		0.20	0.25	Ω	$V_{GS}=10$ V, $I_D=8.5$ A
			0.44			$V_{GS}=10$ V, $I_D=8.5$ A, $T_j=150$ °C
Gate-source leakage current	$I_{GS}$			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	$I_{DS}$			10	μA	$V_{DS}=800$ V, $V_{GS}=0$ V

## ■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		2425.4		pF	$V_{GS}=0$ V, $V_{DS}=50$ V, $f=100$ kHz
Output capacitance	$C_{oss}$		136.0		pF	
Reverse transfer capacitance	$C_{rss}$		3.0		pF	
Turn-on delay time	$t_{d(on)}$		32.6		ns	$V_{GS}=10$ V, $V_{DS}=400$ V, $R_G=2$ Ω, $I_D=8$ A
Rise time	$t_r$		15.9		ns	
Turn-off delay time	$t_{d(off)}$		70.2		ns	
Fall time	$t_f$		6.9		ns	

## ■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		41.2		nC	$I_D=8\text{ A}$ , $V_{DS}=400\text{ V}$ , $V_{GS}=10\text{ V}$
Gate-source charge	$Q_{gs}$		10.8		nC	
Gate-drain charge	$Q_{gd}$		12.4		nC	
Gate plateau voltage	$V_{plateau}$		5.4		V	

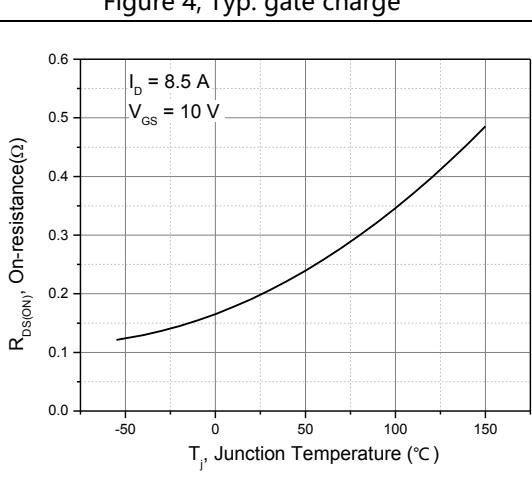
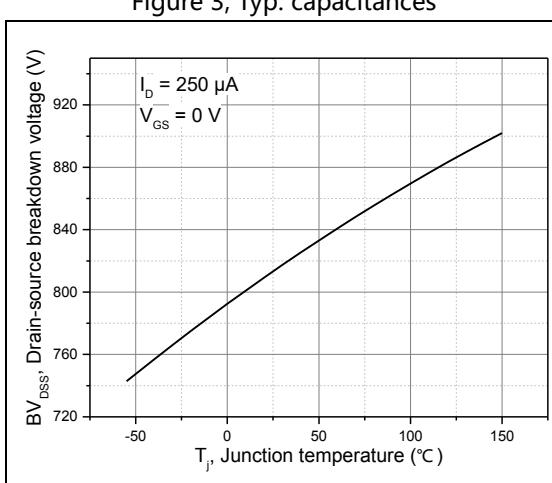
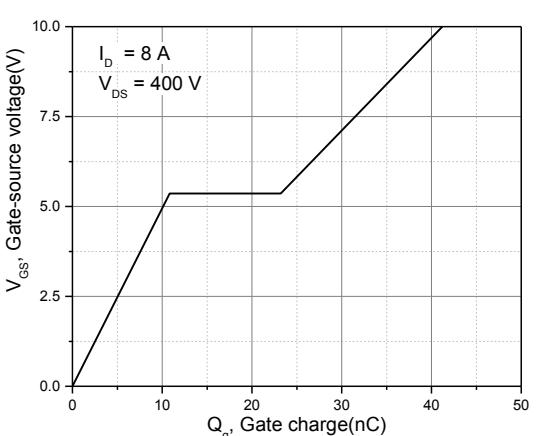
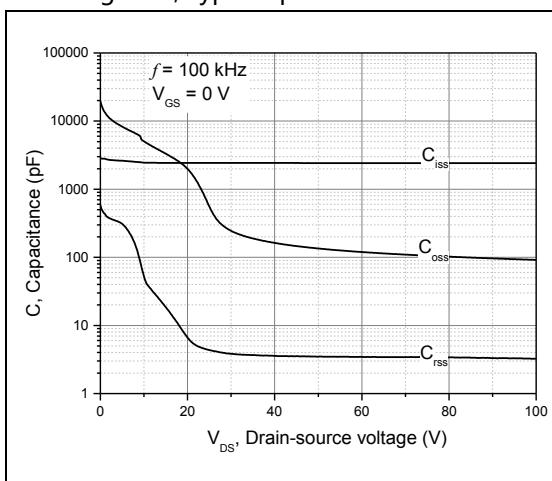
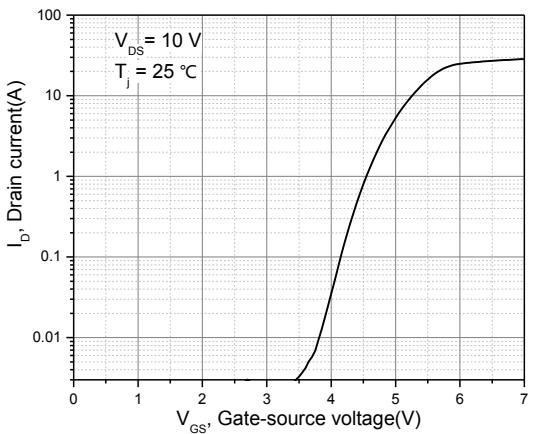
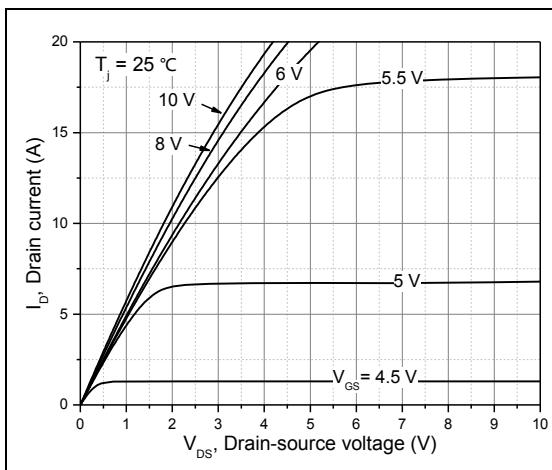
## ■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	$I_S$			17	A	$V_{GS} < V_{th}$
Pulsed source current	$I_{SP}$			51		
Diode forward voltage	$V_{SD}$			1.3	V	$I_S=17\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse recovery time	$t_{rr}$		356.0		ns	$V_R=400\text{ V}$ , $I_S=8\text{ A}$ , $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	$Q_{rr}$		5.2		$\mu\text{C}$	
Peak reverse recovery current	$I_{rrm}$		28.0		A	

## ■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^{\circ}\text{C}$ .
- 5)  $V_{DD}=50\text{ V}$ ,  $R_G=50\text{ }\Omega$ ,  $L=60\text{ mH}$ , starting  $T_j=25\text{ }^{\circ}\text{C}$ .

## ■ Electrical Characteristics Diagrams



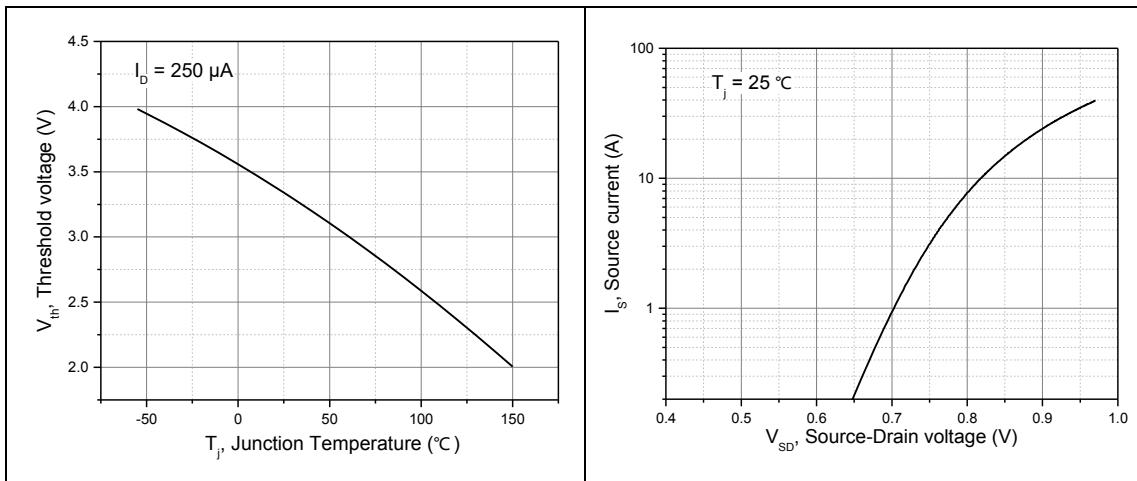


Figure 7, Threshold voltage

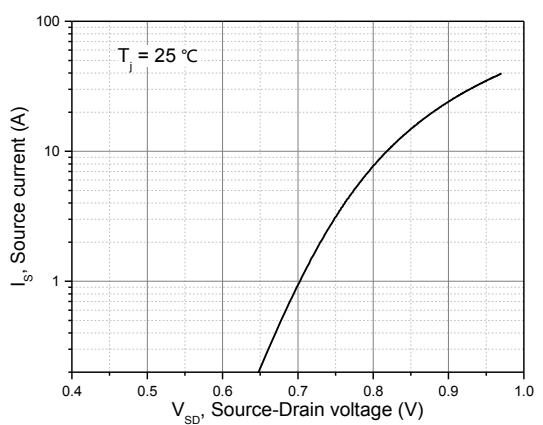


Figure 8, Forward characteristic of body diode

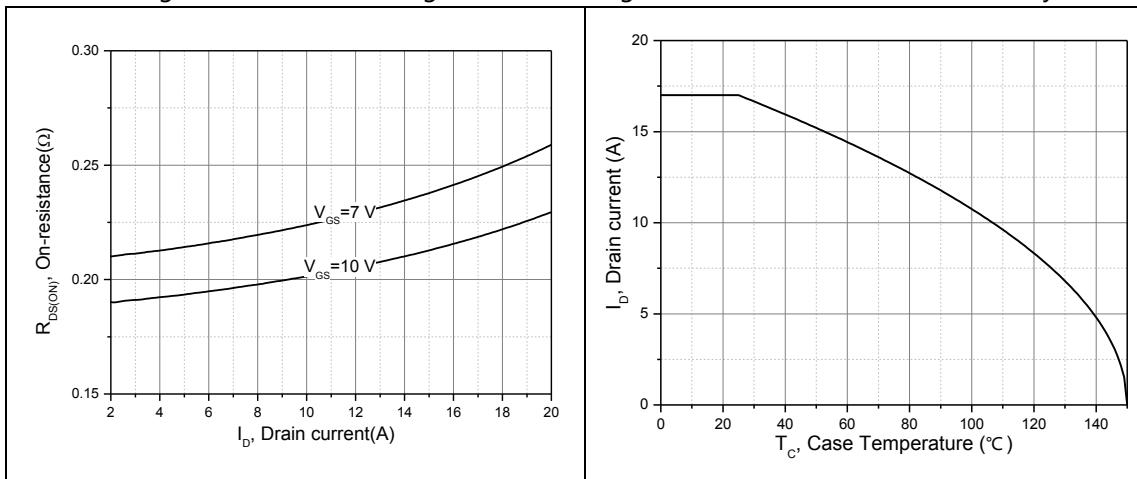


Figure 9, Drain-source on-state resistance

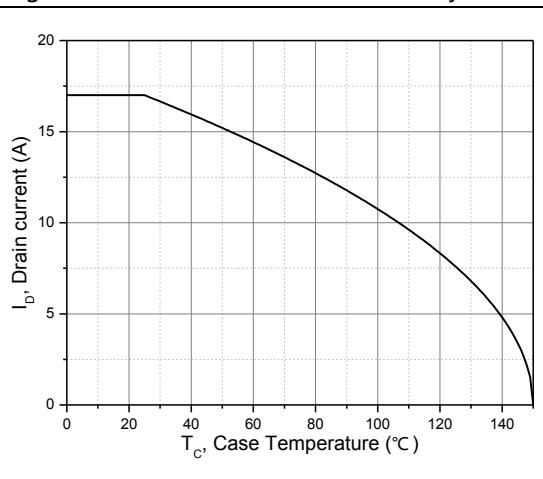


Figure 10, Drain current

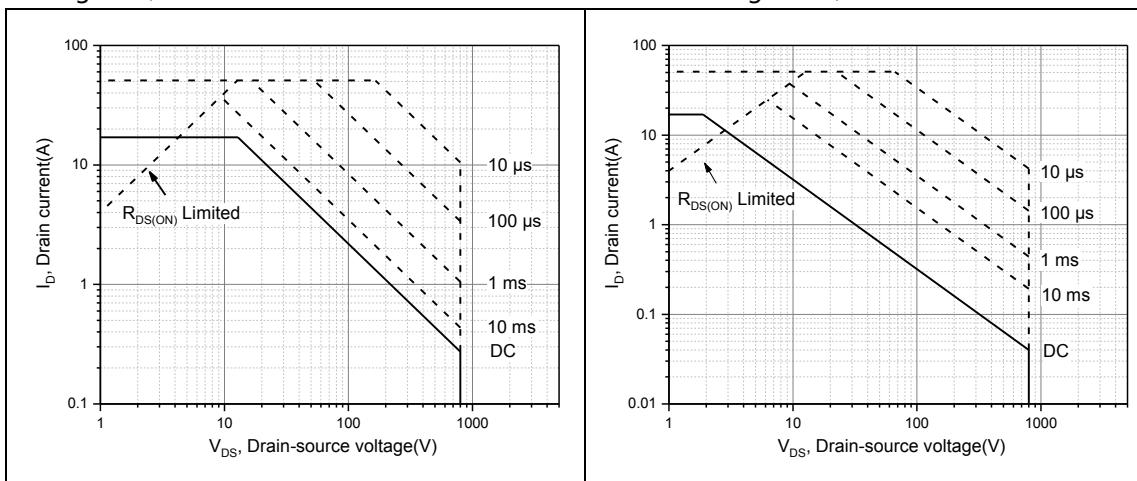


Figure 11, Safe operation area for TO263/TO247

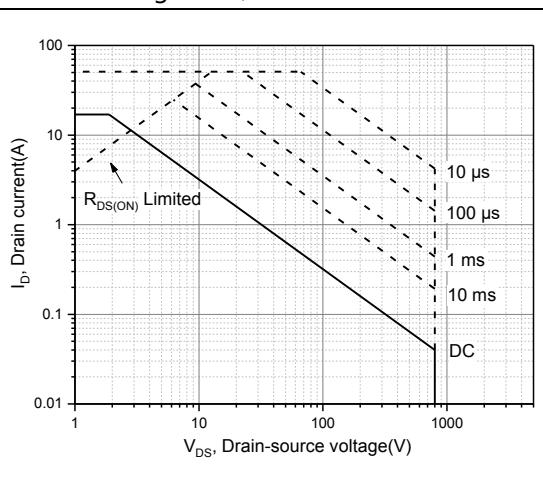
 T<sub>c</sub>=25 °C


Figure 12, Safe operation area for TO220F

 T<sub>c</sub>=25 °C

## ■ Test circuits and waveforms

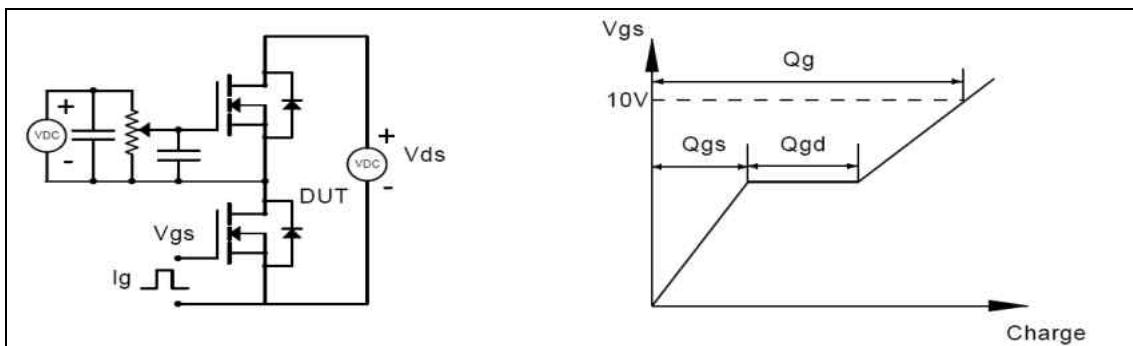


Figure 1, Gate charge test circuit & waveform

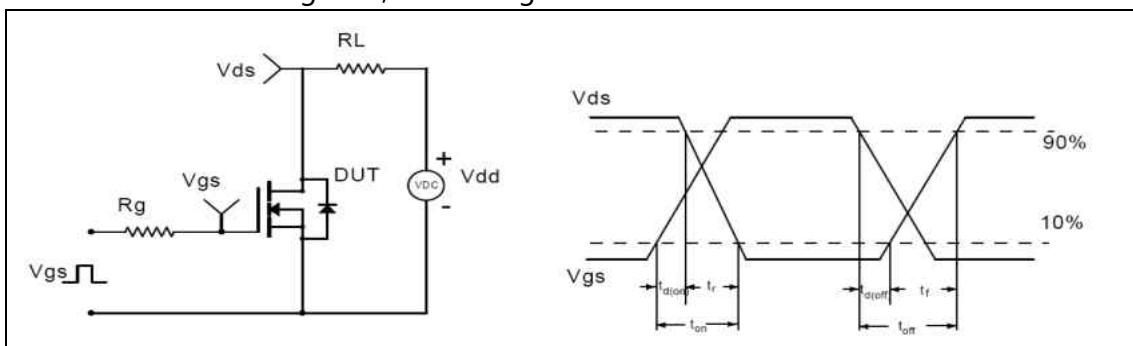


Figure 2, Switching time test circuit & waveforms

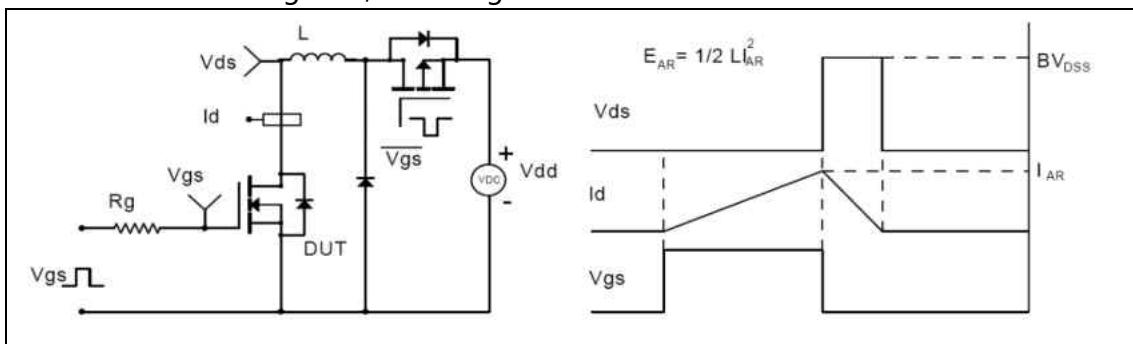


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

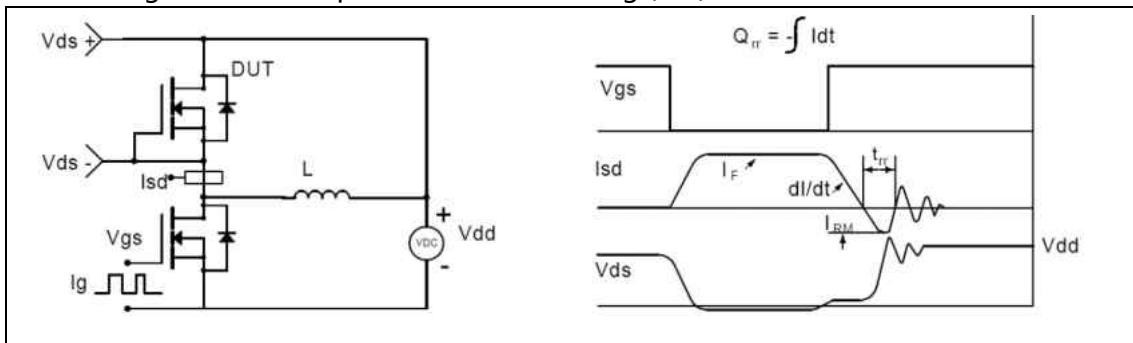
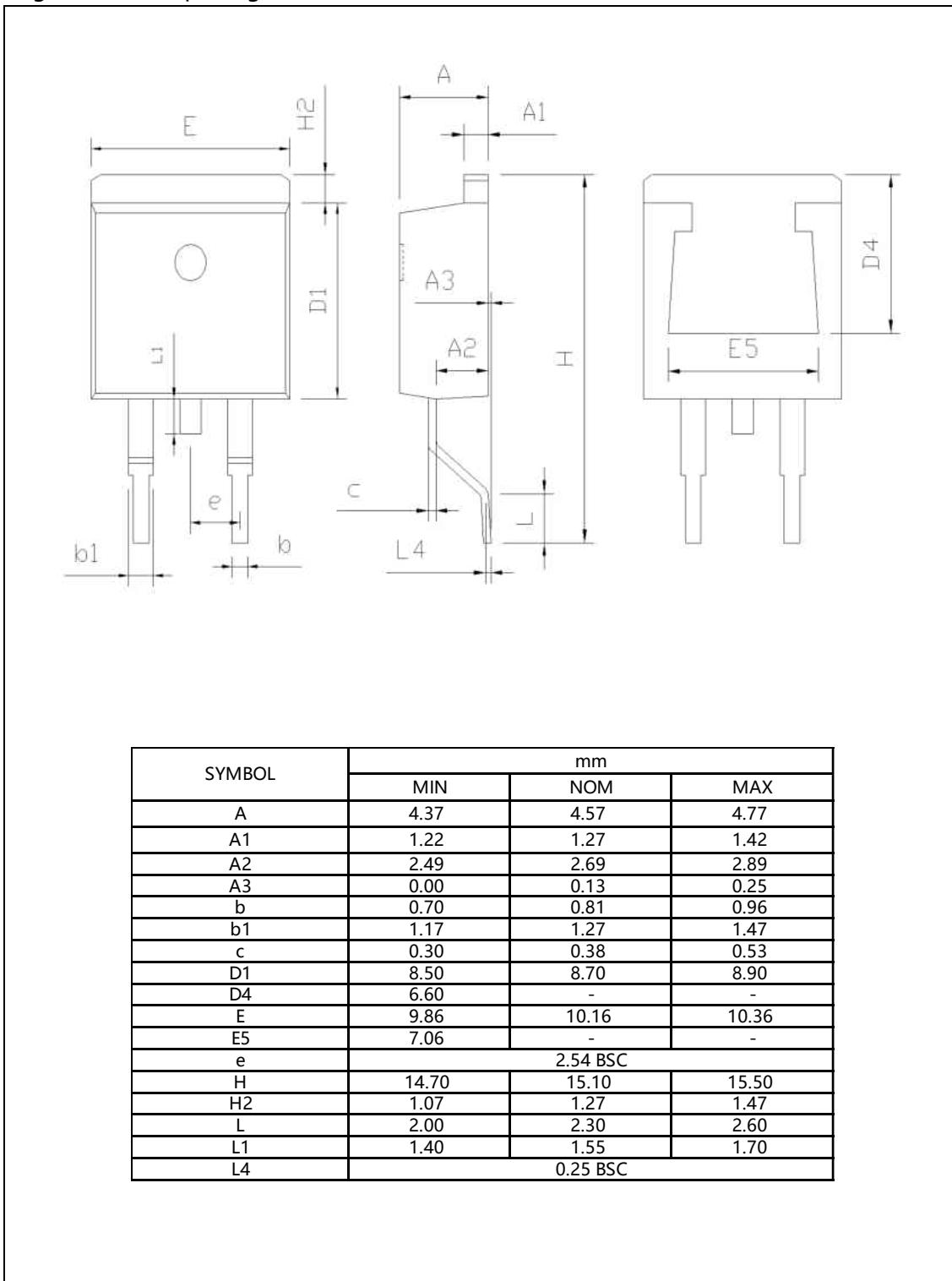


Figure 4, Diode reverse recovery test circuit & waveforms

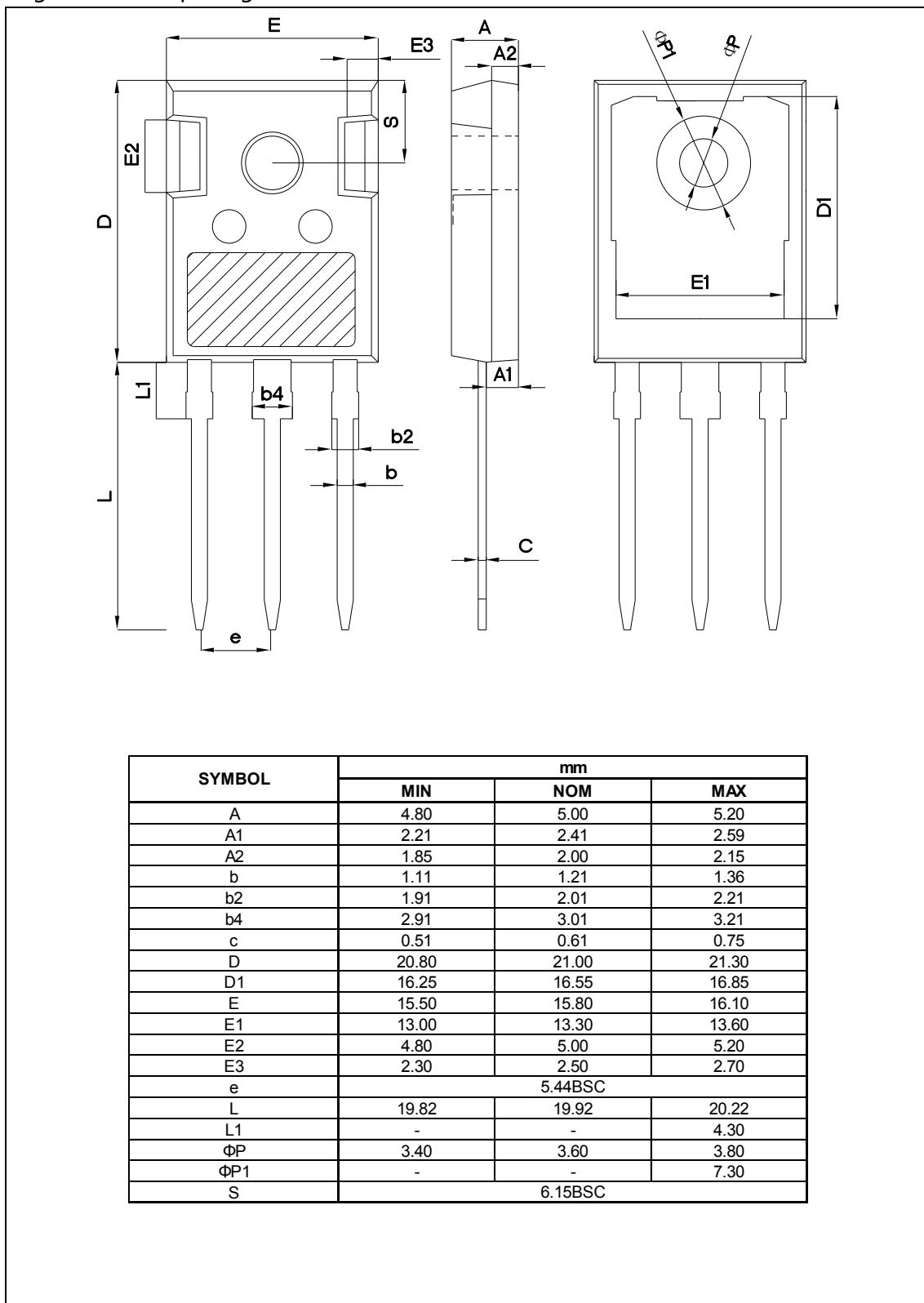
## ■ Package Information

Figure1, TO263 package outline dimension



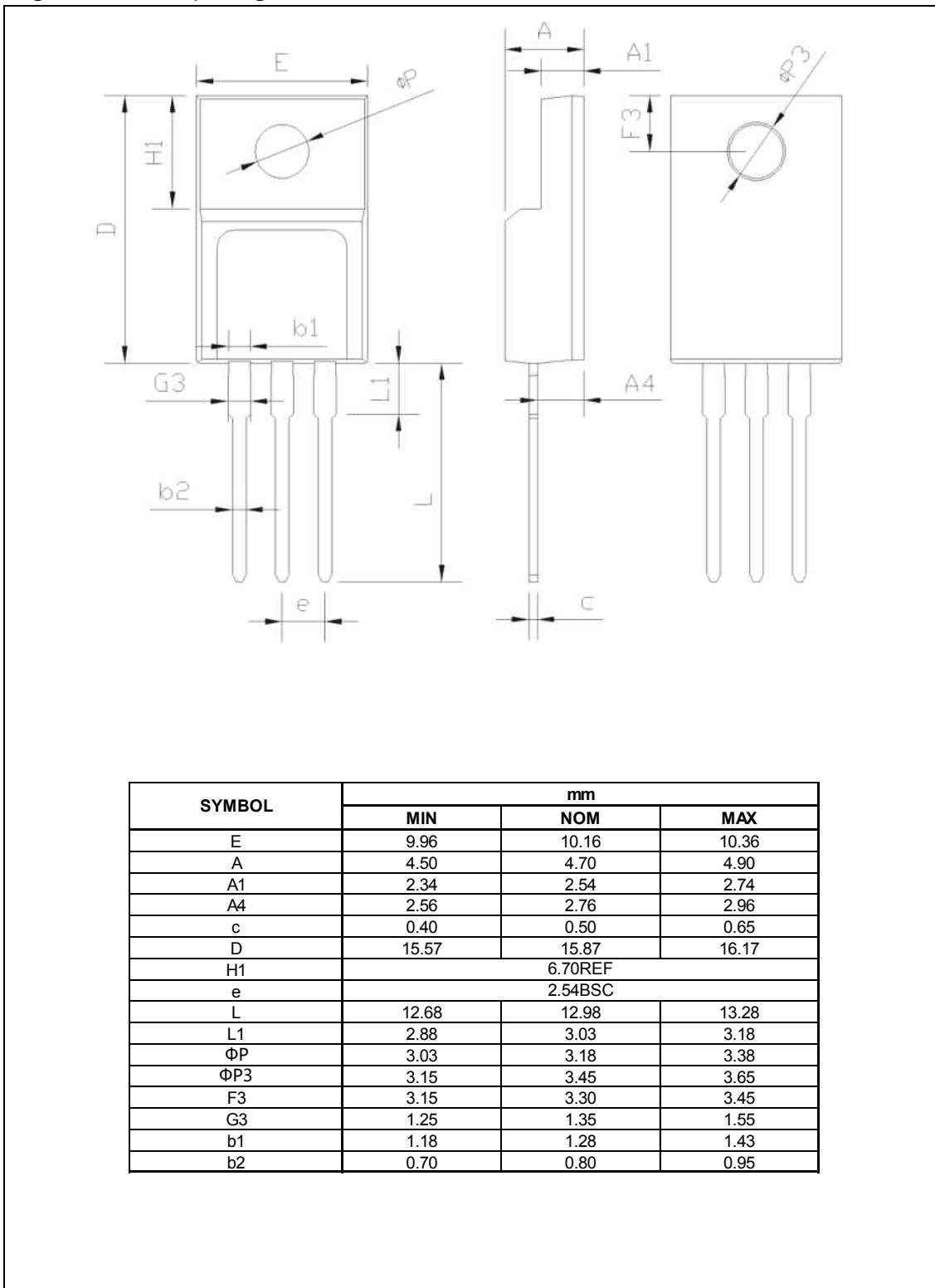
## ■ Package Information

Figure2, TO247 package outline dimension



## ■ Package Information

Figure3, TO220F package outline dimension



## ■ Ordering Information

<b>Package</b>	<b>Units/Tube</b>	<b>Tubes/Inner Box</b>	<b>Units/Inner Box</b>	<b>Inner Box/Carton Box</b>	<b>Units/Carton Box</b>
TO263	50	20	1000	6	6000
TO247	30	11	330	6	1980
TO220F	50	20	1000	6	6000

## ■ Product Information

<b>Product</b>	<b>Package</b>	<b>Pb Free</b>	<b>RoHS</b>	<b>Halogen Free</b>
OSG80R250KF	TO263	yes	yes	yes
OSG80R250HF	TO247	yes	yes	yes
OSG80R250FF	TO220F	yes	yes	yes